

THE



3' to 5' ends

FIG. 4

FIG. 5 is a cross-sectional view of a transistor with a high-voltage region. The transistor includes a substrate 16, a gate stack 12, a source region 10, and a drain region 11. The source region 10 is formed in a P-type substrate 16 and includes a P+ region 13, an N+ region 14, and a P region 15. The drain region 11 is formed in a P-type substrate 16 and includes an N+ region 19. A P+ region 109 is located beneath the source region 10. A P+ region 28 is located beneath the gate stack 12. A P+ region 106 is located beneath the drain region 11. A P+ region 18 is located beneath the gate stack 12. A P+ region 23 is located beneath the gate stack 12. A P+ region 106 is located beneath the drain region 11. A P+ region 18 is located beneath the gate stack 12. A P+ region 23 is located beneath the gate stack 12.

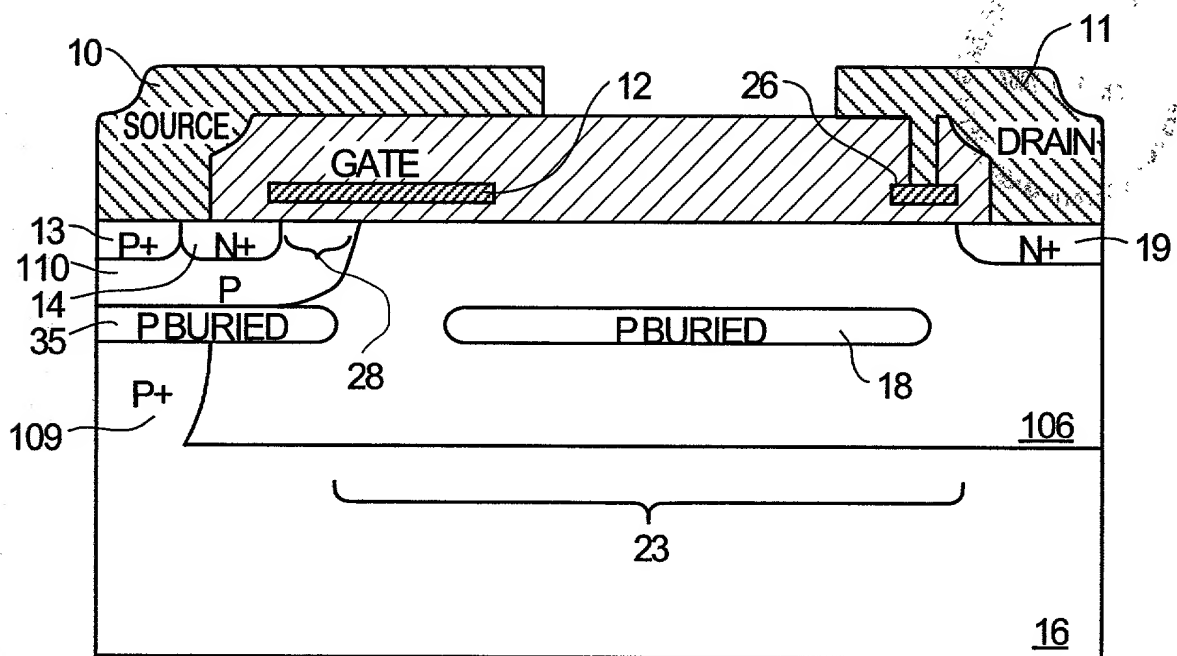


FIG. 5

[illegible][illegible]

FIG. 10 is a cross-sectional view of a semiconductor device. The device includes a substrate 16, a layer 17, and a layer 40. A series of parallel bars 60 are disposed in layer 40, labeled PB1, PB2, and PBn. Each bar 60 is flanked by regions 41. The device is capped by a layer 50, which includes a TAP METAL layer 515 and a layer 542. N+ regions 19 and 700 are also shown.

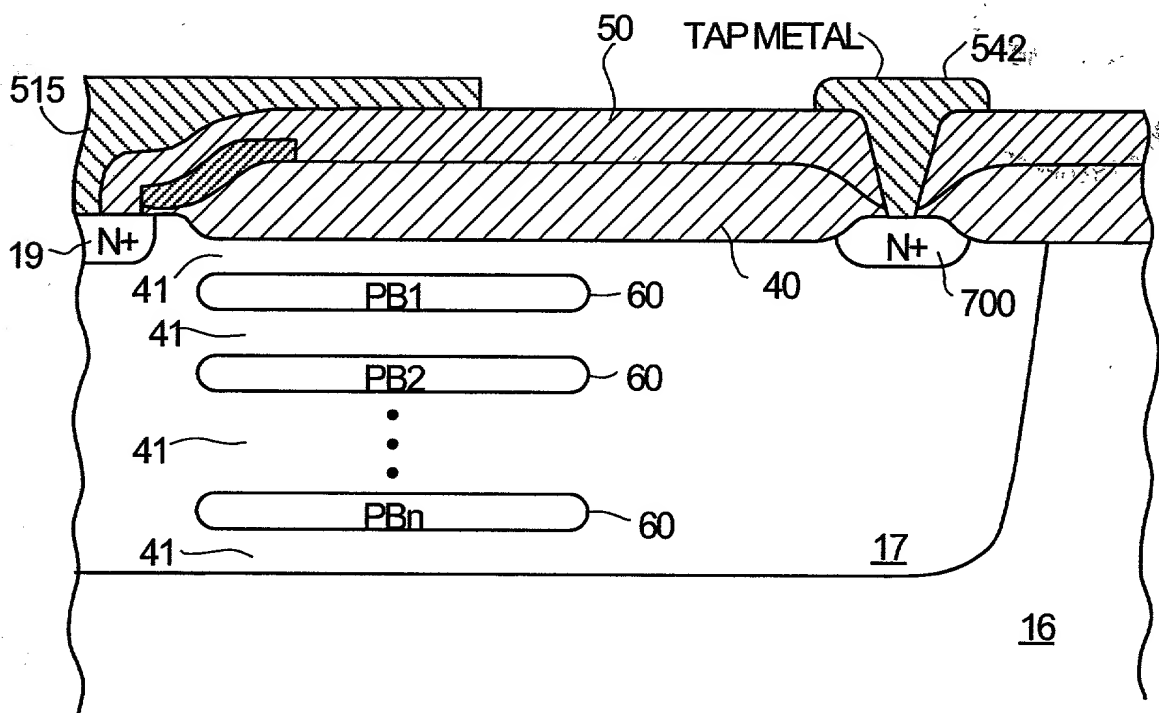


FIG. 10

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NWELL 123

P- 121

FIG. 11a

FIELD OXIDE 125

NWELL 123

P- 121

FIG. 11b

FIELD OXIDE/125

N-TOP 122

P BURIED 130

N-BOT 124NWELL 123

PB 132

P- 121

FIG. 11c

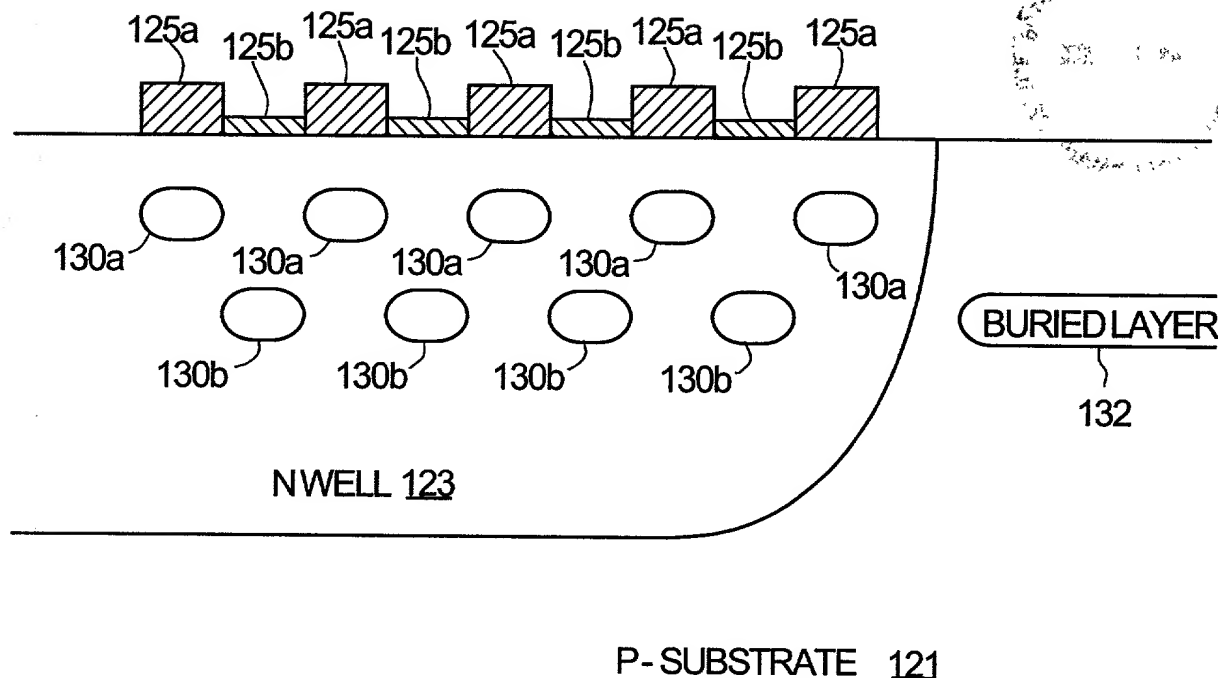


FIG. 11d

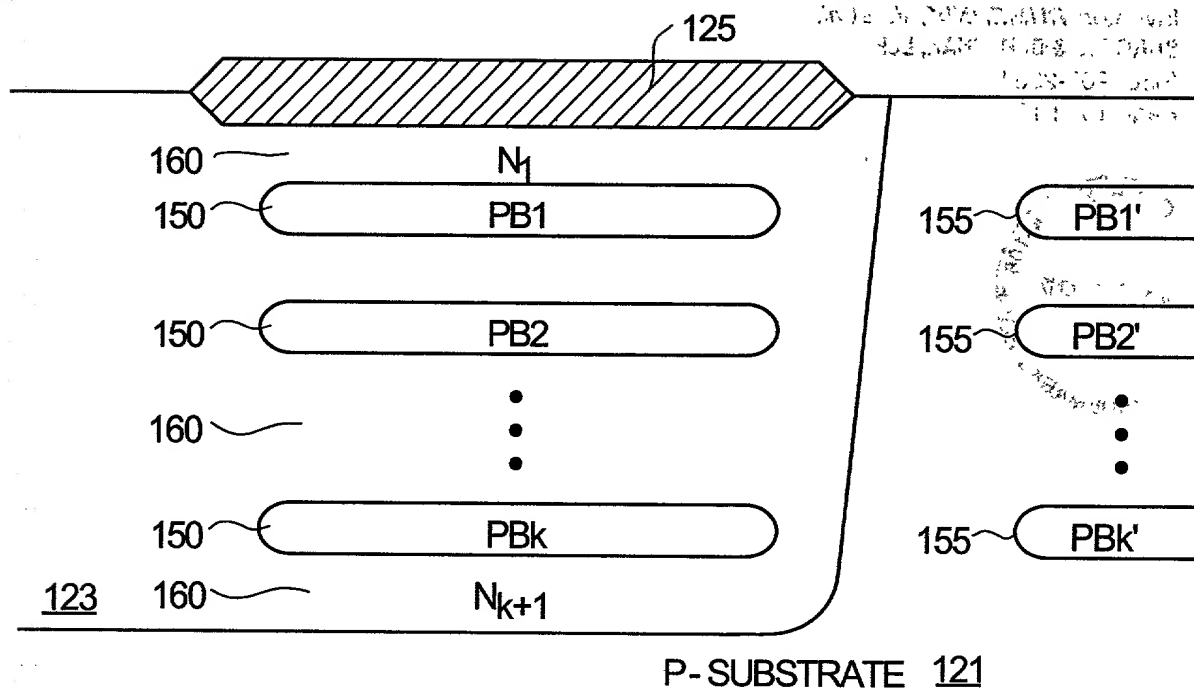


FIG. 11e

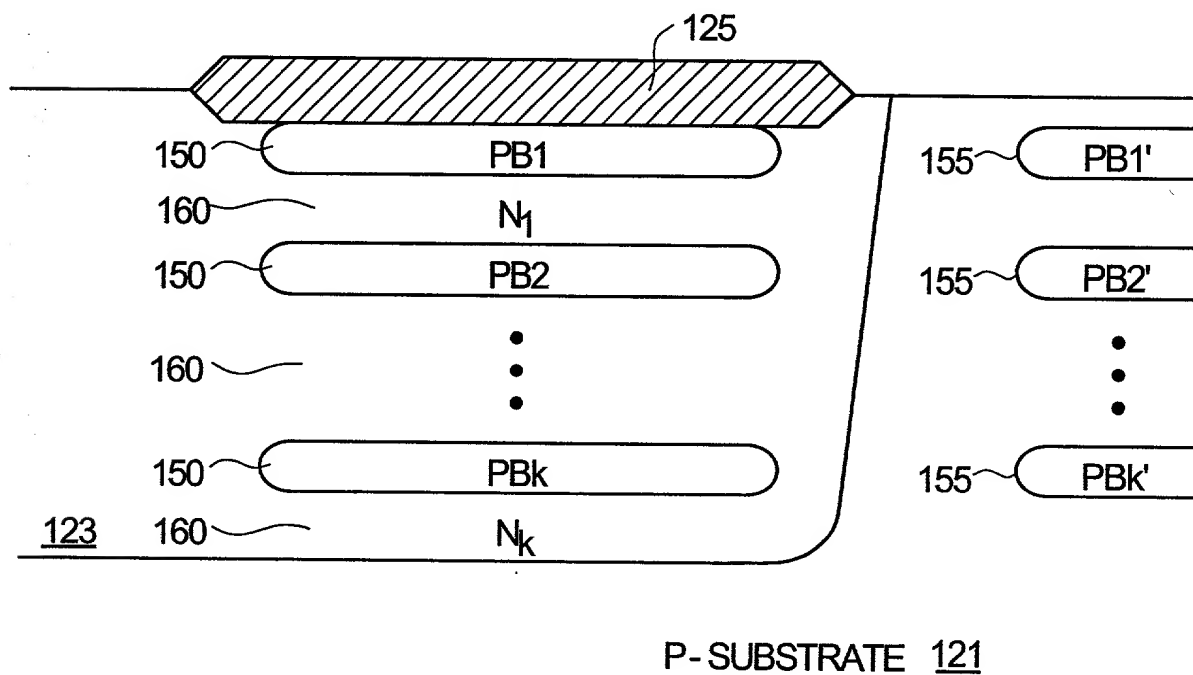


FIG. 11f

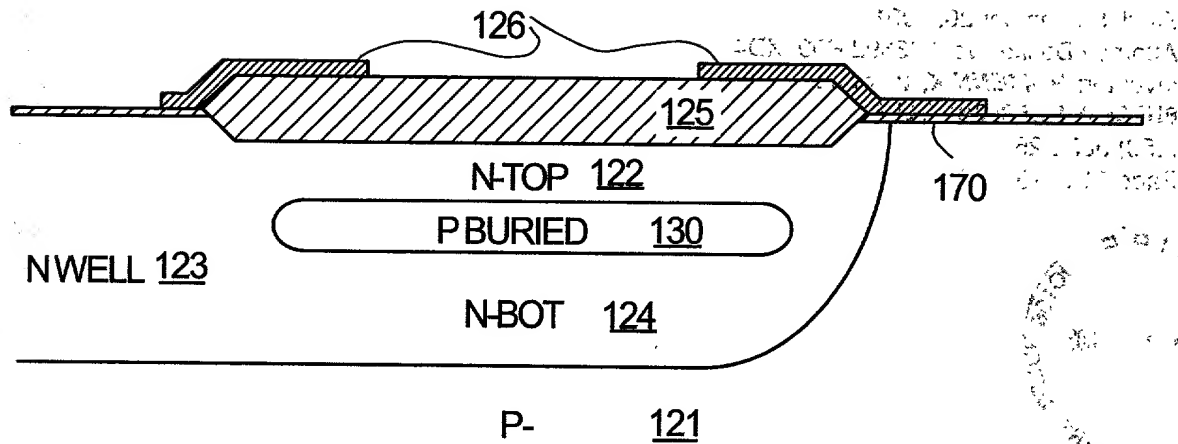


FIG. 11g

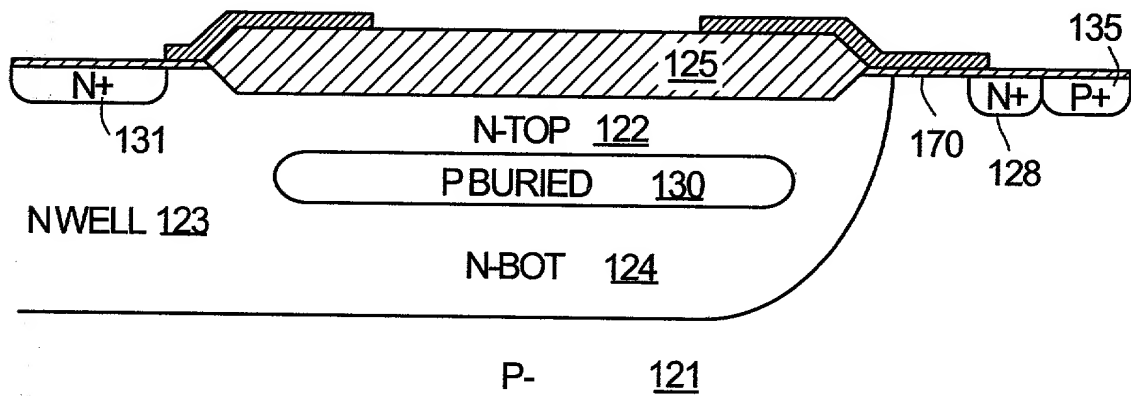


FIG. 11h

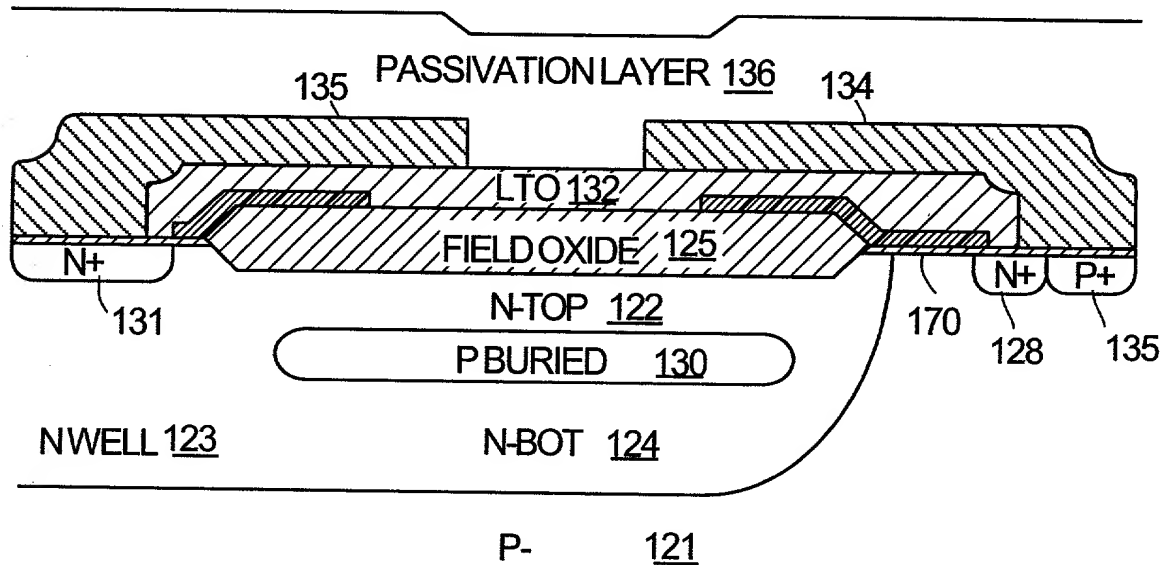


FIG. 11i

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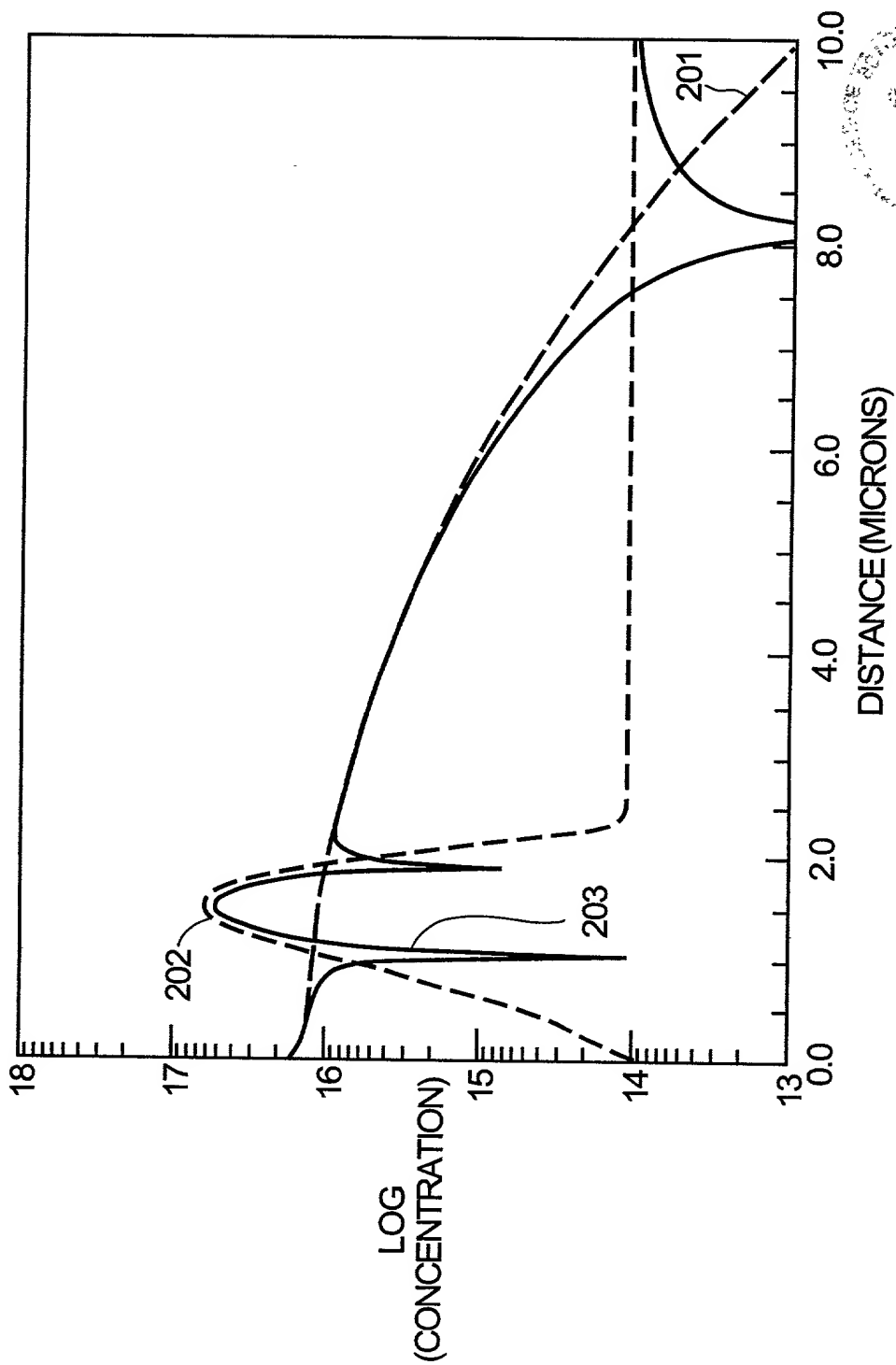


FIG. 12

1. The present invention relates to a method of measuring the concentration of a substance in a material, and more particularly to a method of measuring the concentration of a substance in a material by means of a laser beam.

2. The method of the present invention is based on the principle that the intensity of a laser beam is attenuated as it passes through a material, and the amount of attenuation is proportional to the concentration of the substance in the material.

3. The method of the present invention is particularly useful for measuring the concentration of a substance in a material which is transparent to the laser beam, and which has a uniform thickness.

4. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

5. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

6. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

7. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

8. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

9. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

10. The method of the present invention is also useful for measuring the concentration of a substance in a material which is not transparent to the laser beam, and which has a non-uniform thickness.

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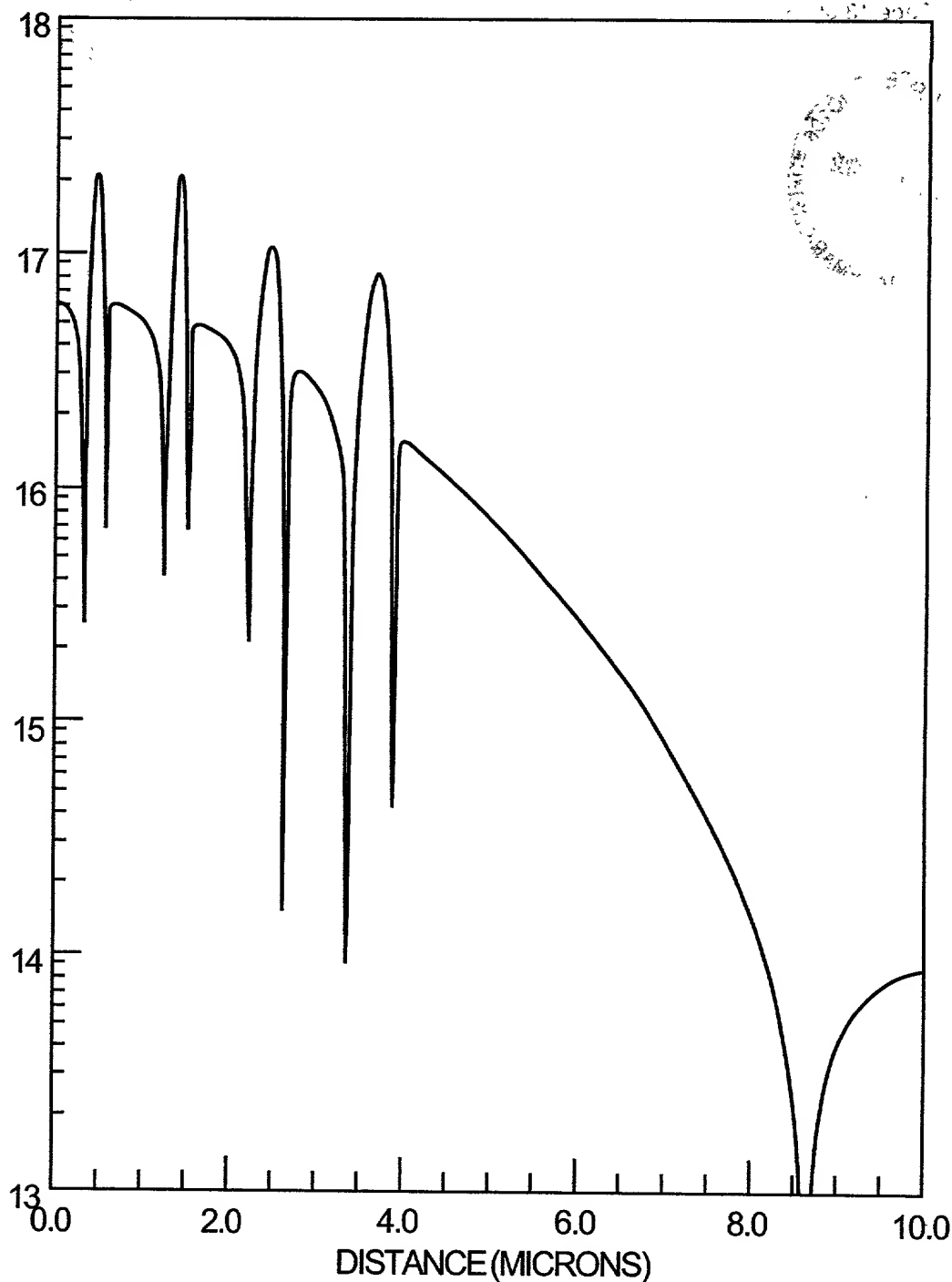


FIG. 13

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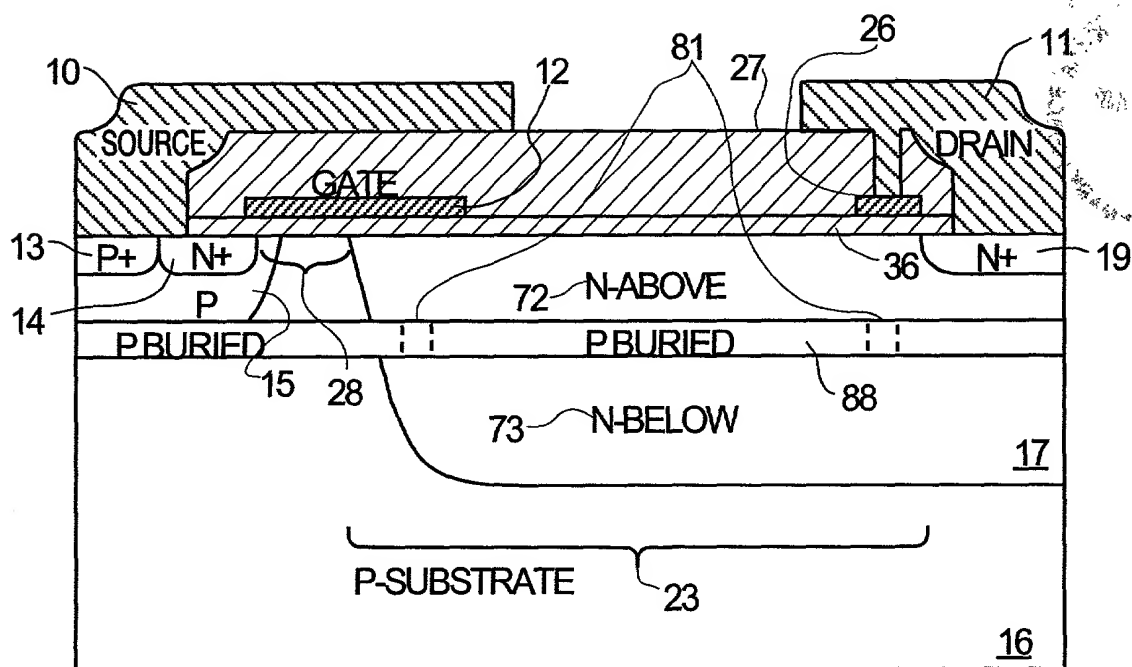


FIG. 14